

SUBMINIATURE SOLID STATE LAMP

AM27SGD09

SUPER BRIGHT GREEN

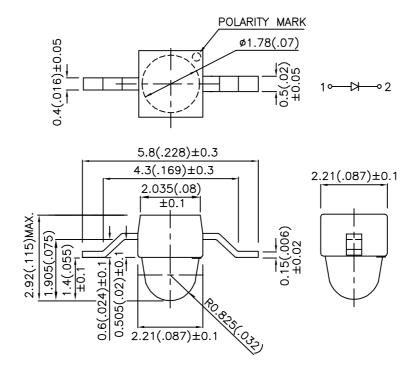
Features

- SUBMINIATURE PACKAGE.
- •WIDE VIEWING ANGLE.
- ●Z-BEND LEAD.
- •LONG LIFE SOLID STATE RELIABILITY.
- •LOW PACKAGE PROFILE.
- •PACKAGE:1000PCS/REEL.
- RoHS COMPLIANT.

Description

The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions



- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25(0.01") unless otherwise noted.
- Lead spacing is measured where the leads emerge from the package.
 Specifications are subject to change without notice.

SPEC NO: DSAD1336 **REV NO: V.3** DATE: MAR/07/2005 **PAGE: 1 OF 4** APPROVED: J. Lu **CHECKED: Allen Liu** DRAWN: W.J.ZHU ERP: 1202000361

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Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20mA		Viewing Angle
			Min.	Тур.	201/2
AM27SGD09	SUPER BRIGHT GREEN (GaP)	GREEN DIFFUSED	2.6	10	40°

Note:

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Green	565		nm	IF=20mA
λD	Dominant Wavelength	Super Bright Green	568		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Green	30		nm	IF=20mA
С	Capacitance	Super Bright Green	15		pF	VF=0V;f=1MHz
VF	Forward Voltage	Super Bright Green	2.2	2.5	V	IF=20mA
IR	Reverse Current	Super Bright Green		10	uA	VR= 5V

Absolute Maximum Ratings at Ta=25°C

Parameter	Super Bright Green	Units
Power dissipation	105	mW
DC Forward Current	25	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	•

Note:

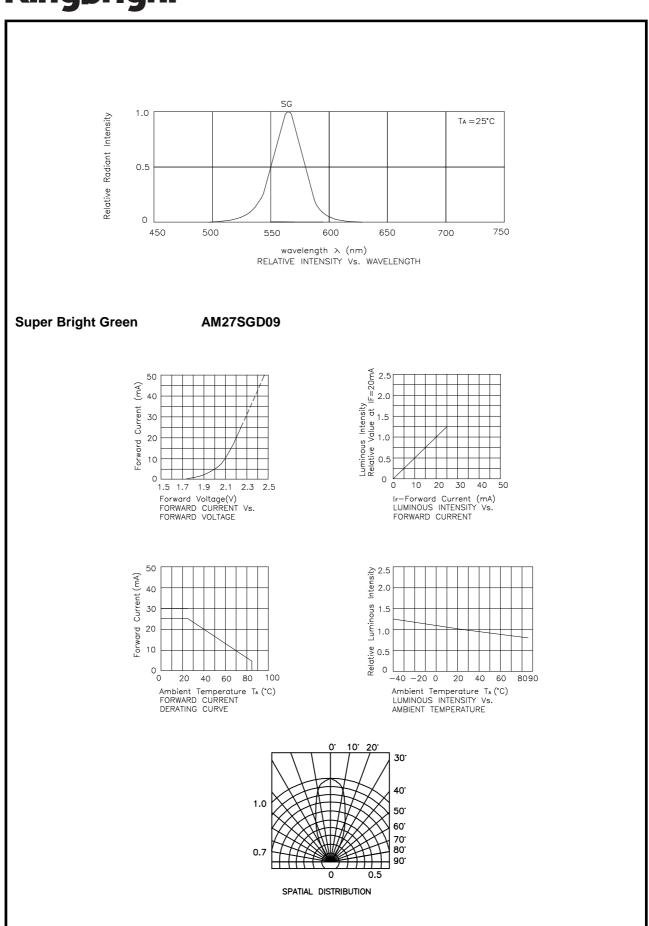
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^{1.} θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

^{1. 1/10} Duty Cycle, 0.1ms Pulse Width.

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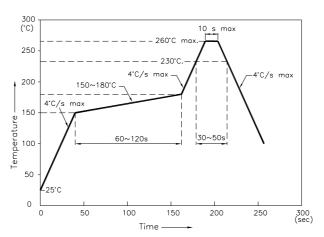
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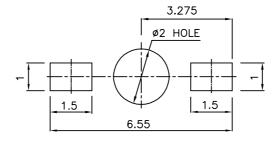
Reflow Soldering Profile For Lead-free SMT Process.



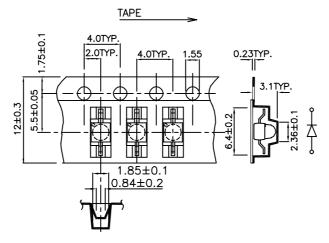
NOTES:

- 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
- 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
- 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm)



Tape Specifications (Units: mm)



Remarks:

If there is sorting requirement (eg. forward voltage, luminous intensity or wavelength), the condition as follows:

- 1. Wavelength: +/-1nm (Test condition is based on the sorting standard).
- 2.Luminous intensity: +/-15% (Test condition is based on the sorting standard).
- 3. Forward voltage: +/-0.1V (Test condition is based on the sorting standard).

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